

MPC555LFMZP40 Information

General information

Package information

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Ordering information

Product/Process Change Notice (PCN)

General Information

Parameter	Value
Part Number	MPC555LFMZP40
Description	MPC555 448KFLASH
Material Type	Tested Packaged Device
Life Cycle Description (code)	PRODUCT STABLE GROWTH/MATURITY(3)
Status	Available

Package Information

Parameter	Value
Package Description	<u>PBGA 272 27*27*1.25P1.27</u>
JEDEC Pkg Description	PBGA-B272
Pin/Lead/Ball Count	272
Package Material	Plastic
Mounting Style	Surface Mount
Tape & Reel	No

Environmental and Compliance Information

Parameter	Value
Pb-Free	No
RoHS Compliant	No
Product Content Report	<u>Product Content Report</u>
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Package Peak Temperature (°C)	235
Replacement Part Number	<u>MPC555LFMVR40</u>
Device Sample Availability	Jun 2005
Device Production Quantity Availability	Jul 2005

Manufacturing and Qualification information

Parameter	Value
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Micron Size (μ m)	0.38
Application/Qualification Tier	COMMERCIAL, INDUSTRIAL, AUTOMOTIVE

Ordering Information

Parameter	Value
Last Order Date	
Last Ship Date	
Minimum Package Quantity (MPQ)	40
MPQ Container	TRAY
Preferred Order Quantity (POQ)	400
POQ Container	BOX
Leadtime (weeks)	16
Export Control Classification Number (US)	3A991
Harmonized Tariff (US)	8542.21.8079
Budgetary Price QTY 1000+ (\$US)	\$49.07
Order	Buy from Distributor

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
11342	Update Notification	<u>UPDATE TO TSPG BAT3 PROBE EXPANSION</u>	08-31-2005	09-27-2005
11262	Process/Product Change Notification	<u>TSPG BAT3 PROBE EXPANSION</u>	08-19-2005	11-17-2005
11122	Process/Product Change Notification	<u>TSPG BAT3 PROBE EXPANSION</u>	07-07-2005	10-05-2005
10742	Product Bulletin	<u>KLM PACKING CHANGE FOR TRAY DEVICES</u>	03-28-2005	04-02-2005
10601	Process/Product Change Notification	<u>TSPG TECD MPC555 REV K3 TO M CONVERSION</u>	02-08-2005	05-09-2005
10422	Process/Product Change Notification	<u>TSPG TECD MOS12 POLYIMIDE FLEX CAPACITY</u>	11-04-2004	02-02-2005
10122	Process/Product Change Notification	<u>TSPG TECD MPC555 PACKED/SHIPPED IN KTM</u>	07-19-2004	10-17-2004
10036	Product Bulletin	<u>RE-ISSUE TSPG TECD MPC555 REV K3 FINAL TEST XFER</u>	06-21-2004	06-22-2004
9851	Product Bulletin	<u>TSPG TECD MPC555 REV K3 FINAL TEST XFER</u>	05-04-2004	05-05-2004
9048	Product Bulletin	<u>TIC SUPPORT FOR QUALITY QUERIES IN EMEA</u>	08-04-2003	08-05-2003

7616	Product Bulletin	MPC5XX DEVICE MARKING IMPROVEMENT	05-31-2002	06-01-2002
7495	Product Bulletin	MPC555 FINAL ROOM TEST ELIMINATION	05-10-2002	05-11-2002
7499	Product Bulletin	MPC555 CCTS COLD TEST ELIMINATION	05-10-2002	05-11-2002
6785	Product Bulletin	MPC555 REV K3 MASK CHANGE	10-18-2001	10-19-2001
6516	Product Bulletin	MPC555 IBIDEN SUBSTRATE	07-05-2001	07-06-2001
6517	Product Bulletin	MPC555 UIMB ERRATA	06-22-2001	06-23-2001
6388	Product Bulletin	MPC555 REV K2 & REV K3 ONO PROCESS	05-01-2001	05-02-2001
6290	Product Bulletin	MPC555 QSMCM SCI2 ERRATA UPDATE	03-26-2001	03-27-2001
6095	Update Notification	UPDATE TO PB 6025 MPC555 SCI2 ERRATA TYPOGRAPHICAL ERRORS	11-17-2000	11-18-2000
6025	Product Bulletin	MPC555 QSMCM SCI2 ERRATA	10-27-2000	10-28-2000
5825	Product Bulletin	MPC555 J750 TEST PLATFORM CONVERSION	08-22-2000	08-23-2000